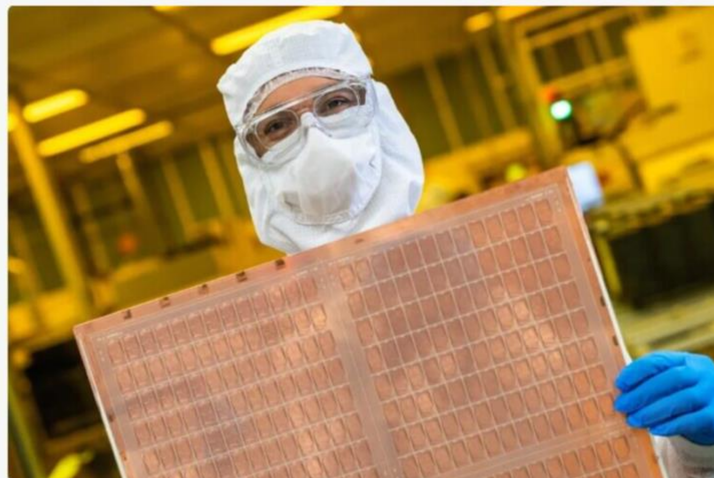
Silicon Austria Labs and EV Group Strengthen Collaboration in Optical Technology Research – November 17, 2023



IFTLE 575: Intel's Interest in Glass Core Substrates

Intel recently announced that it would use glass core substrates for advanced packaging in the second half of this decade. The company reports it has been researching and evaluating the reliability of glass core substrates as a replacement for organic substrates for more than a decade.

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AT&S' Markus Leitgeb and Tony Gueli Talk About Meeting Today's IC Substrate Challenges

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Member of the Week

PulseForge, Inc. utilizes applied energy in a precise and targeted manner to enable innovation in industrial manufacturing. Its expertise and tools empower customers to explore novel materials and manufacturing methodologies, driving dynamic and efficient production at an industrial scale. Suitable for wafer-level and panel-level packaging, PulseForge Photonic Debonding offers ash-free wafer separation with fewer contaminants and lower cost compared to lasers. It can also be used on warped wafers without hardware or process changes. This is partly due to PulseForge not being a point source like lasers, but its beam is homogenous even at a 10 mm Z distance from the lamp. This makes the chip-embedded EMC wafers market (Fan-out packages) uniquely suitable for photonic debonding. Photonic Debonding is also uniquely suited for chip-embedded EMC wafers (fan-out packages) capable of debonding warped wafers without any hardware or process changes. The PulseForge soldering tools offer on-wafer bumping at a fraction of the time and thermal budget so sensitive architectures don't get damaged. Plus, the company offer tools for unique cleaning solutions for ultra-fine-pitch features, dehydrogenation, and even novel TFT designs.

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Community News

Silicon Austria Labs and EV Group Strengthen Collaboration in Optical Technology Research

Events Calendar

COMPASS 2023
November 21, 2023

EVG NIL Technology Day 2023
November 29, 2023

ERS electronic Introduces "High Power Dissipation" Thermal Chuck System, Which Can Dissipate up to 2.5kW at -40°C for Embedded Processors, DRAM and NAND Wafer Test

ClassOne Technology Receives Order for Solstice® S8 Single-Wafer System from Finland's VTT Technical Research Centre

IEEE P3405: Chiplet Interconnect Test and Repair Working Group (CITR-WG)

Global Semiconductor Manufacturing Industry Set for Q4 2023 Recovery, SEMI Reports

25th IEEE Electronics Packaging Technology Conference
December 5-8, 2023

69th Annual IEEE International Electron Devices Meeting
December 9-13, 2023

SEMICON Japan 2023
December 13-15, 2023

Recommended Reads

What Can Go Wrong In Heterogeneous Integration – SemiEngineering

Imec Grants Public Access to Virtual Fab for Quantifying Environmental Impact of IC Manufacturing – Semiconductor Digest

US Govt Says Banned Chipmaking Equipment Still Ends Up in China – Tom's Hardware

Total Overlay With Multiple RDL Layers – SemiEngineering

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